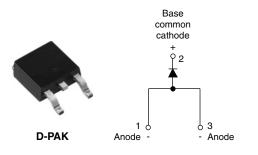


Vishay High Power Products

Surface Mountable Fast Soft Recovery Diode, 8 A



PRODUCT SUMMARY							
V _F at 8 A	< 1.3 V						
t _{rr}	80 ns						
V _{RRM}	1000/1200 V						

FEATURES/DESCRIPTION

The 8EWF..SPbF fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.



COMPLIANT

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

This series is designed and qualified for industrial level and lead (Pb)-free.

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

MAJOR RATINGS AND CHARACTERISTICS									
SYMBOL	CHARACTERISTICS	VALUES	UNITS						
I _{F(AV)}	Sinusoidal waveform	8	А						
V _{RRM}		1000/1200	V						
I _{FSM}		170	А						
V _F	8 A, T _J = 25 °C	1.3	V						
t _{rr}	1 A, 100 A/μs	80	ns						
TJ	Range	- 40 to 150	°C						

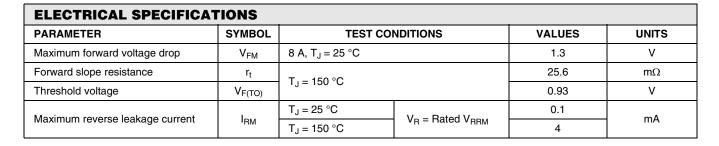
VOLTAGE RATINGS									
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I _{RRM} AT 150 °C mA						
8EWF10SPbF	1000	1100	4						
8EWF12SPbF	1200	1300	4						

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum average forward current	I _{F(AV)}	$T_C = 94$ °C, 180° conduction half sine wave	8						
Maximum peak one cycle non-repetitive surge current	I _{FSM}	10 ms sine pulse, rated V _{RRM} applied	170	А					
		10 ms sine pulse, no voltage reapplied	reapplied 200						
Maximum I ² t for fusing	l ² t	10 ms sine pulse, rated V _{RRM} applied	144	A ² s					
	1-1	10 ms sine pulse, no voltage reapplied	200	A-5					
Maximum I ² \sqrt{t} for fusing	l²√t	t = 0.1 to 10 ms, no voltage reapplied	2000	A²√s					

* Pb containing terminations are not RoHS compliant, exemptions may apply



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RECOVERY CHARACTERISTICS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Reverse recovery time	t _{rr}	I _F at 8 Apk	270	ns	I _{FM}				
Reverse recovery current	I _{rr}	25 A/µs	4.2	А					
Reverse recovery charge	Q _{rr}	T _J = 25 °C	1	μC	di/ Q _{rr}				
Snap factor	S		0.6		¥ I _m				

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		- 40 to 150	°C				
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	2.5	°C M/				
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA} ⁽¹⁾		50	°C/W				
Soldering temperature	T _S	For 10 seconds	240	°C				
Approximate weight			1	g				
Approximate weight			0.03	OZ.				
Marking device		Case style D-PAK (TO-252AA)	8EWF12S					

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994



Surface Mountable Vishay High Power Products Fast Soft Recovery Diode, 8 A

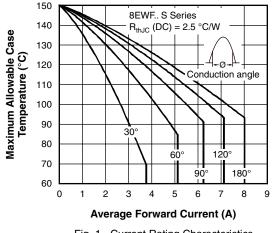


Fig. 1 - Current Rating Characteristics

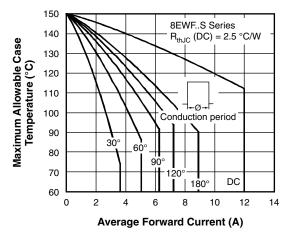


Fig. 2 - Current Rating Characteristics

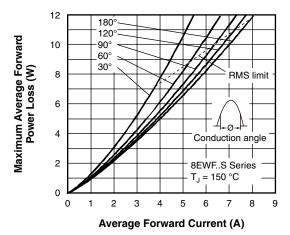


Fig. 3 - Forward Power Loss Characteristics

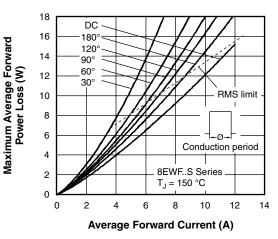
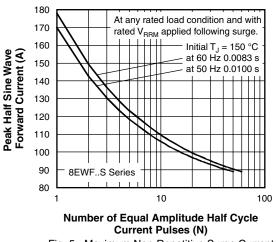
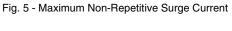
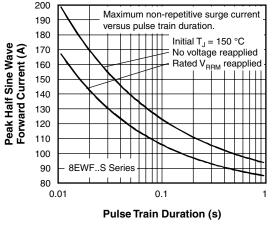


Fig. 4 - Forward Power Loss Characteristics









Vishay High Power Products

Surface Mountable Fast Soft Recovery Diode, 8 A

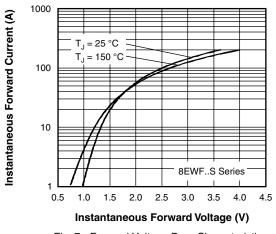


Fig. 7 - Forward Voltage Drop Characteristics

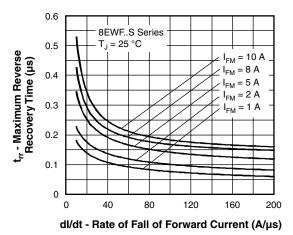


Fig. 8 - Recovery Time Characteristics, $T_J = 25 \degree C$

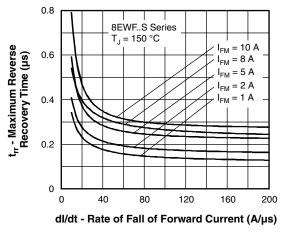
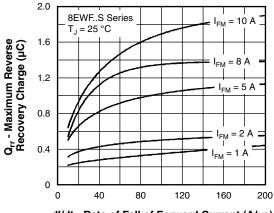
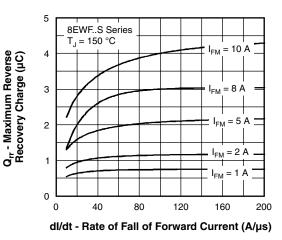


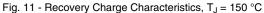
Fig. 9 - Recovery Time Characteristics, $T_J = 150 \ ^\circ C$



dl/dt - Rate of Fall of Forward Current (A/µs)

Fig. 10 - Recovery Charge Characteristics, $T_J = 25 \ ^{\circ}C$





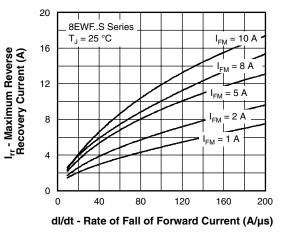


Fig. 12 - Recovery Current Characteristics, $T_J = 25 \ ^{\circ}C$



Surface Mountable Vishay High Power Products Fast Soft Recovery Diode, 8 A

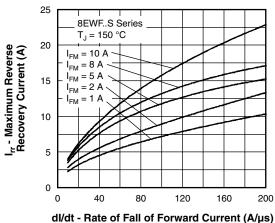


Fig. 13 - Recovery Current Characteristics, $T_J = 150$ °C

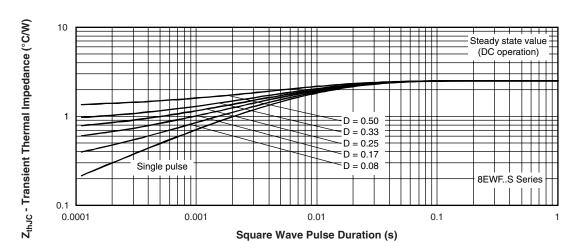


Fig. 14 - Thermal Impedance ZthJC Characteristics



Vishay High Power Products

S Surface Mountable Fast Soft Recovery Diode, 8 A

ORDERING INFORMATION TABLE

Device code	8	E	W	F	12	S	TR	PbF		
	1	2	3	4	5	6	7	8		
	1 - 2 -	Circ	uit conf	ng (8 = a iguratior	-					
	3 -	- Pac	E = Single diode Package: W = D-PAK							
	4		e of silio Fast so							
	5 - 6 -		tage coo Surface	10 = 1000 V 12 = 1200 V						
	7		-	e and re		ht orien	ted)			
	8 -	• N	one = S	pe and i tandard ad (Pb)-	product		ed)			

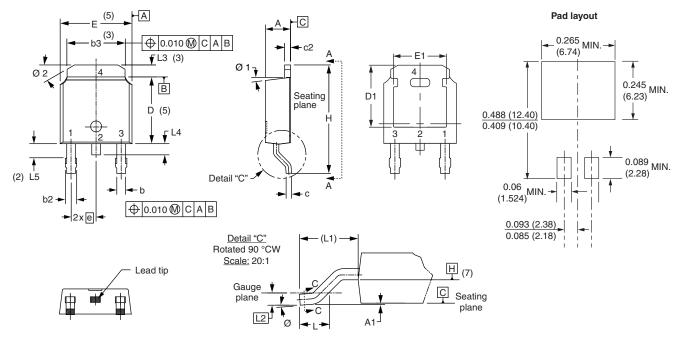
LINKS TO RELATED DOCUMENTS						
Dimensions	http://www.vishay.com/doc?95016					
Part marking information	http://www.vishay.com/doc?95059					
Packaging information	http://www.vishay.com/doc?95033					



Vishay Semiconductors

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		S NOTES		SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51 BSC		0.020 BSC		
с	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

⁽⁴⁾ Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC outline TO-252AA

Document Number: 95016



Vishay

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